Half-Bridge Bipolar Switch

FEATURES

- Source or Sink 4.0A
- Supply Voltage to 35V
- High-Current Output Diodes
- Tri-State Operation
- TTL and CMOS Input Compatibility
- Thermal Shutdown Protection
- 300kHz Operation
- Low-Cost TO-220 Package

DESCRIPTION

This device is a monolithic integrated circuit designed to provide high-current switching with low saturation voltages when activated by low-level logic signals. Source and sink switches may be independently activated without regard to timing as a built-in interlock will keep the sink off if the source is on.

This driver has the high current capability to drive large capacitive loads with fast rise and fall times; but with high-speed internal flyback diodes, it is also ideal for inductive loads. Two UC2950s can be used together to form a full bridge, bipolar motor driver compatible with high frequency chopper current control.

TRUTH TABLE

Source Drive Pin 2	Sink Drive Pin 5	Output Pin 4
Low	Low	Low
Low	High	Off
High	Low	High
High	High	High

Note: With no load, output voltage will be HIGH in the OFF state.

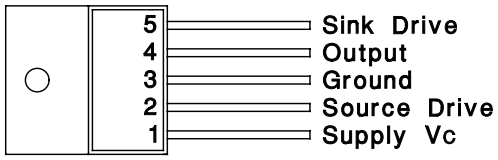
ABSOLUTE MAXIMUM RATINGS (Note 1)

Supply Voltage Range, V_C . . . . . 8V to 35V
Output Voltage Range, V_O . . . . . –3.0V to V_C+3V
Input Voltage Range, V_{IN} . . . . . –0.3V to +7.0V
Peak Output Current (100 ms, 10% DC) . . . . . ± 4.0A
Continuous Output Current . . . . . ± 2.0A
Power Dissipation with Heat Sink 15W
Power Dissipation in Free Air 2W
Operating Temperature Range, T_A . . . . . –20°C to +100°C
Storage Temperature Range, T_S . . . . . –55°C to +125°C

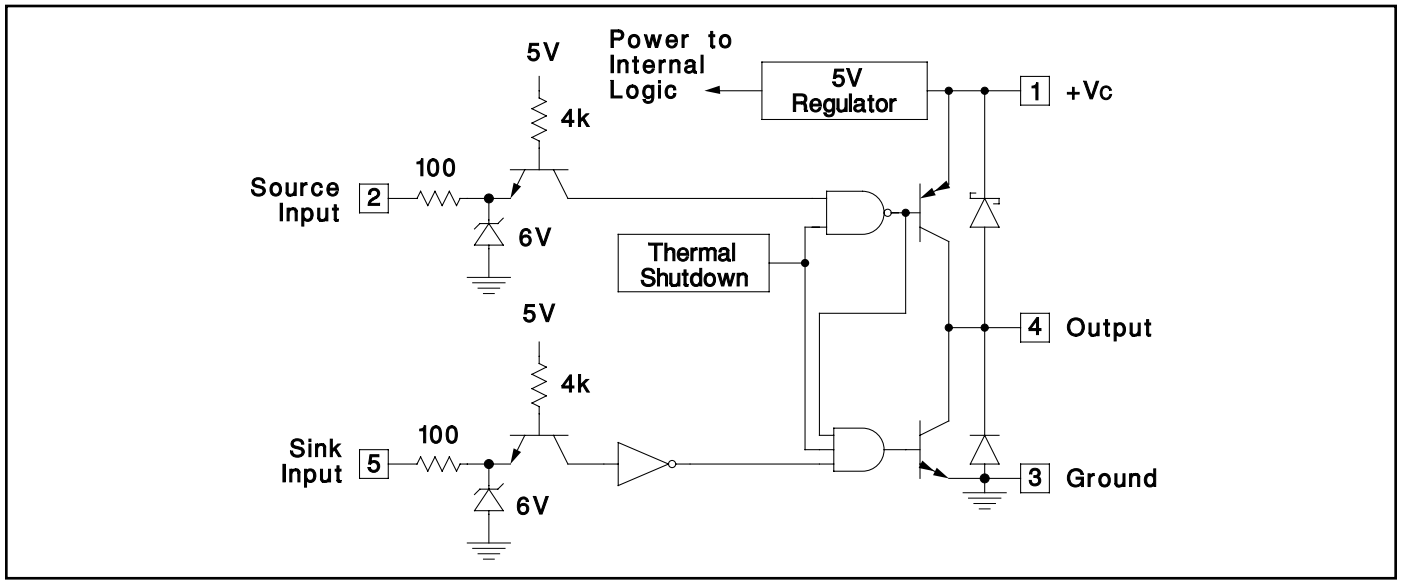
Note 1: Consult Packaging section of databook for thermal limitations and considerations of package.

CONNECTION DIAGRAM

5-PIN TO-220 (TOP VIEW)
T Package



SIMPLIFIED SCHEMATIC



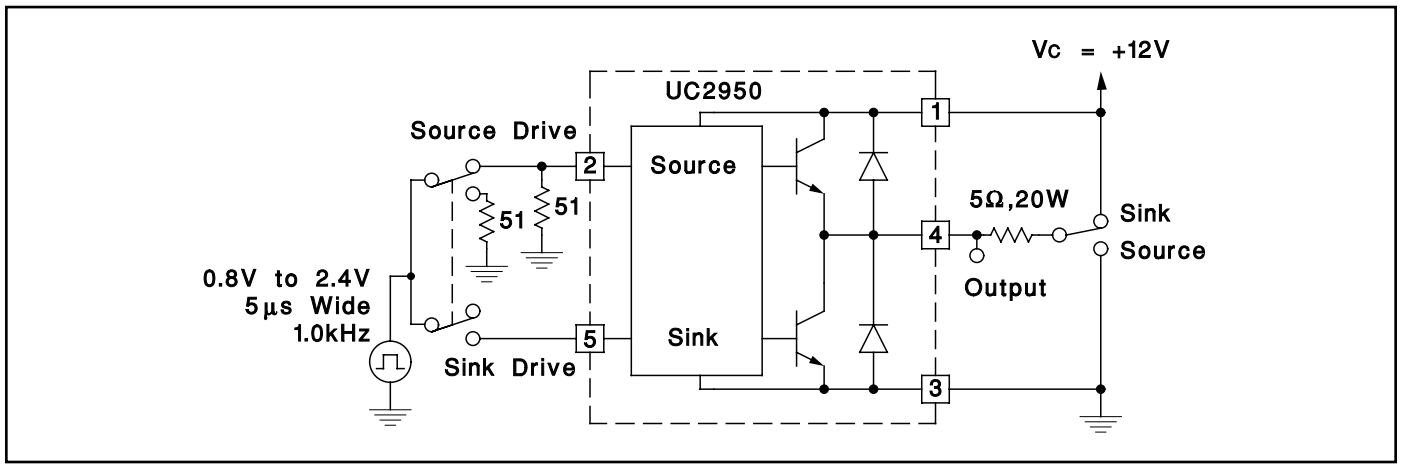
ELECTRICAL CHARACTERISTICS: Unless otherwise stated, V_C = 35V, T_A = -20°C to +100°C, V_{IL} = 0.8V, V_{IH} = 2.4V for either input, $T_A = T_J$.

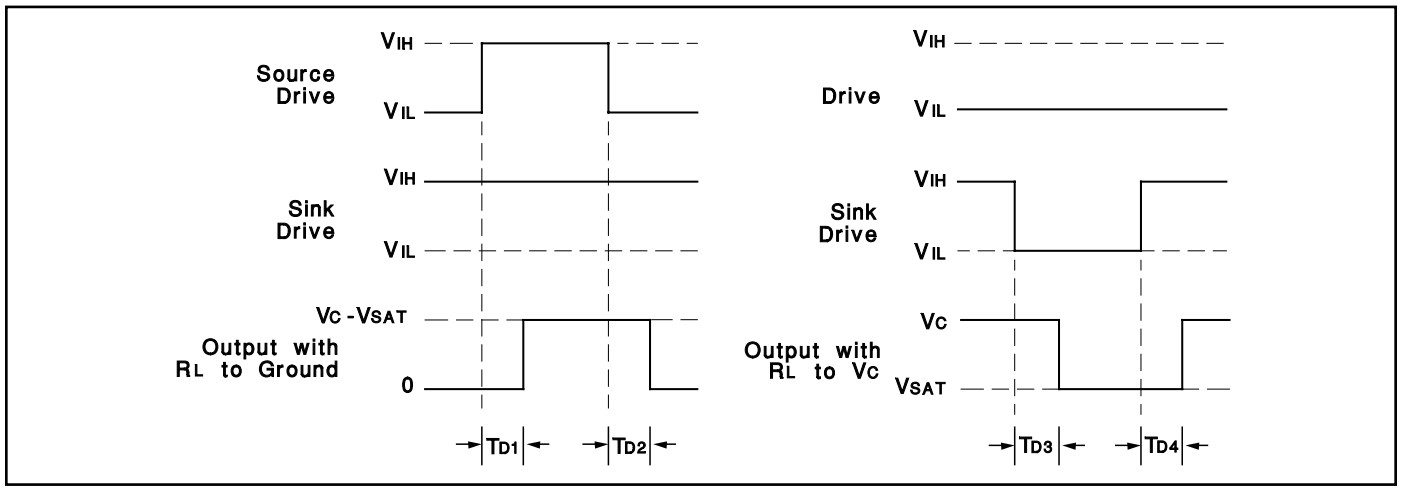
PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output Leakage to V_C	Output Off		20	500	µA
Output Leakage to Ground	Output Off		–200	–500	µA
Output Sink Saturation	V_{OL}, I_L = 2.0A		1.2	2.0	V
Output Source Saturation	(V_C-V_{OL}), I_L = –2.0A		1.2	2.0	V
Sink Diode Forward Voltage	I_D = –2.0A		1.4	2.0	V
Source Diode Forward Voltage	I_D = 2.0A		1.4	2.0	V
Input Current	Either Input, V_I = 5V		20	100	µA
	Either Input, V_I = 0V		–1.0	–1.6	mA
Supply Current	Output High		20	36	mA
	Output Low		10	20	mA

SWITCHING CHARACTERISTICS: See Test Circuit. V_C = 12V, R_L = 5Ω, T_A = 25°C. Guaranteed by design, not 100% tested in production.

PARAMETERS	MIN	TYP	MAX	UNITS
Source Turn-On Delay, t_{D1}		300	500	ns
Source Turn-Off Delay, t_{D2}		1.0	2.0	µs
Sink Turn-On Delay, t_{D3}		200	400	ns
Sink Turn-Off Delay, t_{D4}		100	300	ns
Cross-Conduction Current Spike When Source and Sink are Activated Together		0.6	1.0	µs

SWITCHING TEST CIRCUIT





PACKAGING INFORMATION

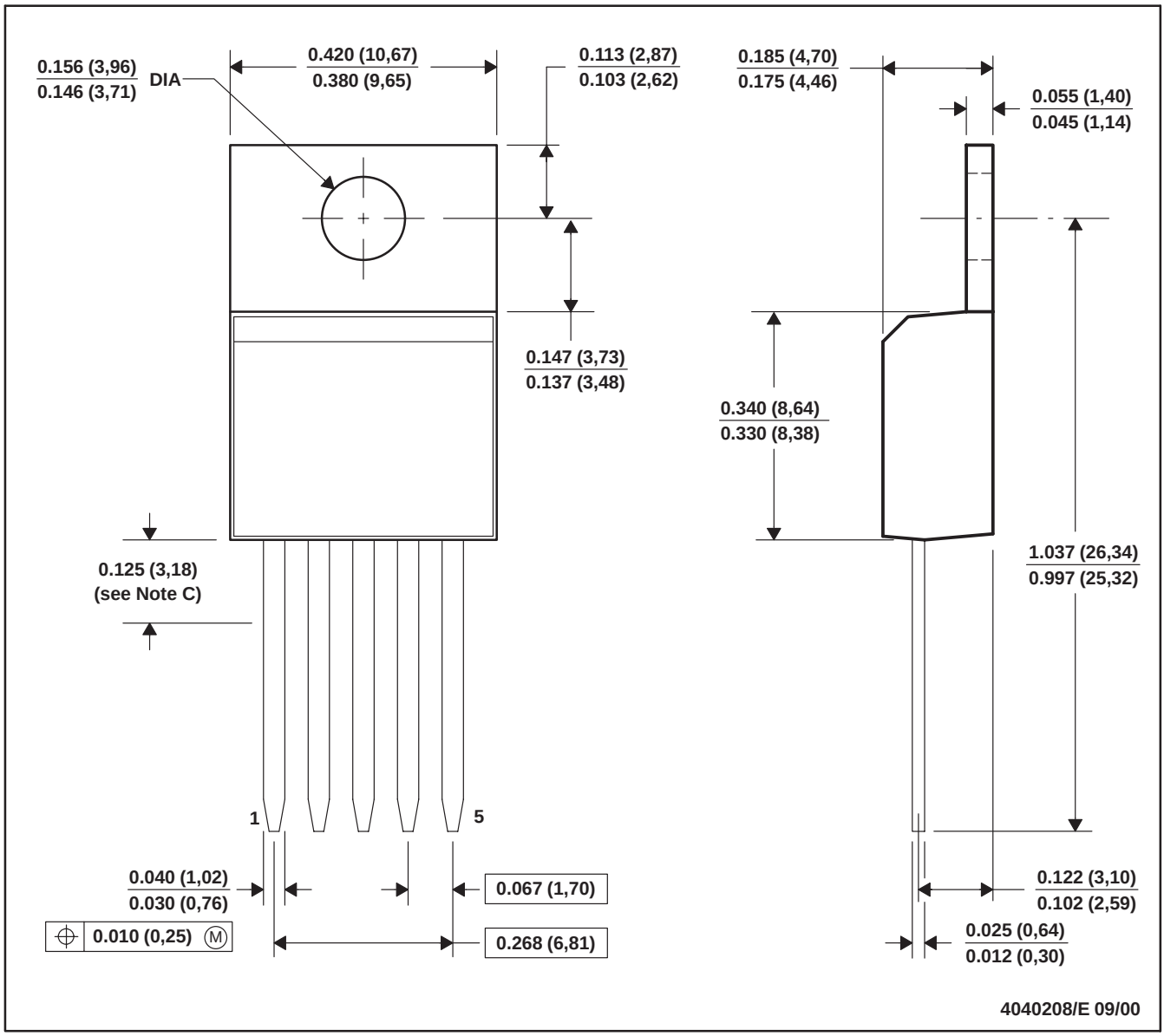
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
UC2950T	ACTIVE	TO-220	KC	5	50	None	CU SN	Level-NA-NA-NA

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

KC (R-PSFM-T5) **PLASTIC FLANGE-MOUNT**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Lead dimensions are not controlled within this area.
D. All lead dimensions apply before solder dip.
E. The center lead is in electrical contact with the mounting tab.

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